



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of: **Miwa KOZAWA et al.**

Group Art Unit: **1756**

Application Number: **10/670,291**

Examiner: **Daborah Chacko-Davis**

Filed: **September 26, 2003**

Confirmation No.: **6427**

For: **RESIST PATTERN THICKENING MATERIAL, PROCESS FOR
FORMING RESIST PATTERN, AND PROCESS FOR
MANUFACTURING SEMICONDUCTOR DEVICE**

Attorney Docket Number: **031181**
Customer Number: **38834**

AMENDMENT AFTER FINAL REJECTION

Mail Stop AF
Commissioner for Patents
P. O. Box 1450
Alexandria, VA 22313-1450

November 20, 2006

Sir:

This paper is filed in response to the Office Action dated August 22, 2006.

Amendments to the Claims begin on page 2 of this paper.

Remarks begin on page 7 of this paper.